

## QUERY CONTROL FORM

Application No. 10/026,135Prepared by WExaminer-GAU Stone - 1735Date 5/23/04No. of queries 1

## RTIS USE ONLY

Tracking Number 05949259Week Date 5-10-04RU-18-17W

## JACKET

- |                      |                        |                    |                |
|----------------------|------------------------|--------------------|----------------|
| a. Serial No.        | f. Foreign Priority    | k. Print Claim(s)  | p. PTO-1449    |
| b. Applicant(s)      | g. Disclaimer          | l. Print Fig.      | q. PTOL-85b    |
| c. Continuing Data   | h. Microfiche Appendix | m. Searched Column | r. Abstract    |
| d. PCT               | i. Title               | n. PTO-270/328     | s. Sheets/Figs |
| e. Domestic Priority | j. Claims Allowed      | o. PTO-892         | t. Other       |

## SPECIFICATION

- a. Page Missing
- b. Text Continuity
- c. Holes through Data
- d. Other Missing Text
- e. Illegible Text
- f. Duplicate Text
- g. Brief Description
- h. Sequence Listing
- i. Appendix
- j. Amendments
- k. Other

## CLAIMS

- a. Claim(s) Missing
- b. Improper Dependency
- c. Duplicate Numbers
- d. Incorrect Numbering
- e. Index Disagrees
- f. Punctuation
- g. Amendments
- h. Bracketing
- i. Missing Text
- j. Duplicate Text
- k. Other

## MESSAGE

PTO 1449- Please either initial or line  
through citations. (Copy provided for reference)

Thank You  
initials pm

## RESPONSE

initials

# LIST OF REFERENCES CITED BY APPLICANT

(Use serials and dates if necessary)

ATTY. DOCKET NO.  
100970.665047US1

SERIAL NO.  
10026135

APPLICANT

Pedigo, Jesse et al

FILING DATE

20 December 2001

GROUP

To be determined

## U.S. PATENT DOCUMENTS

EXAMINER DATE	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA 6,454,154	09/24/02	Filling Device	228	33	12/28/00
	BB 5,893,404	04/13/99	Method and Apparatus for Metal Solid Freeform Fabrication Utilizing Partially Solidified Metal Slurry	164	71.1	09/20/96
	CC 4,496,275	02/12/85	Rotary Filing and Capping Apparatus	53	506	07/06/81
	DD					
	EE					
	FF					
	GG					
	HH					
	II					

## FOREIGN PATENT DOCUMENTS

EXAMINER DATE	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
	JJ					YES NO
	KK					
	LL					
	MM					
	NN					

## OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

OO	
EXAMINER	DATE CONSIDERED

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

## LIST OF REFERENCES CITED BY APPLICANT

(Use several sheets if necessary)



OFFICE RECEIVED

100067 00071052

CLASSIFICATION

Jesse Pedigo, et al

TITLE

12-20-01

RECEIVED

100067 00071052

CLASSIFICATION

Jesse Pedigo, et al

TITLE

12-20-01

APR 09 2002

TC 1700

## U.S. PATENT DOCUMENTS

U.S. PATENT NO.	INVENTOR	DATE	TITLE	CLASS.	NO. OF PAGES	U.S. PATENT NO.
15	3,601,523	08/24/71	Through Hole Connectors	174	885	06/19/70
	4,106,187	08/15/78	Curved Rigid Printed Circuit Boards	29	625	01/10/76
	4,283,343	08/11/81	Use of Photosensitive Solum to Create Through-Hole Connections in Circuit Boards	156	237	03/20/80
	4,360,570	11/23/82	Use of Photosensitive Solum to Create Through-Hole Connections in Circuit Boards	428	596	06/15/81
	4,622,239	11/11/86	Method and Apparatus for Dispensing Viscous Materials	427	96	02/18/86
	4,700,474	10/20/87	Apparatus and Method for Temporarily Sealing Holes in Printed Circuit Boards	29	846	11/26/85
	4,777,721	10/18/88	Apparatus and Method for Temporarily Sealing Holes in Printed Circuit Boards Utilizing a Thermodeformable Material	20	846	10/15/87
	4,783,247	11/8/88	Method and Manufacture for Electrically Insulating Base Material Used in Plated-Through Printed Circuit Panels	204	1811	05/15/86
	4,884,337	12/07/89	Method for Temporarily Sealing Holes in Printed Circuit Boards Utilizing a Thermodeformable Material	29	846	10/15/87
	4,954,313	09/04/90	Method and Apparatus for Filling High Density Vias	419	9	02/03/89
	4,964,948	10/23/90	Printed Circuit Board Through Hole Technique	136	659	11/13/89
	4,995,941	02/26/91	Method of Manufacture Interconnect Device	156	630	05/15/89
	5,053,921	10/01/91	Multi-layer Interconnect Device and Method of Manufacture Thereof	361	386	10/21/90
	5,058,265	10/22/91	Method for Packaging a Board of Electronic Components	26	852	09/10/90
	5,117,869	05/26/92	Circuit Board Fabrication	174	261	09/28/90
	5,133,120	07/28/92	Method of Filling Conductive Material into Through Holes of Printed Wiring Board	29	852	03/15/91
	5,145,691	09/08/92	Apparatus for Packing Filler into Through-Holes or the Like in a Printed Circuit Board	425	110	03/22/91
	5,220,723	06/27/93	Process for Preparing Multi-Layer Printed Wiring Board	19	830	11/04/91
15	5,274,916	01/04/94	Method of Manufacturing Ceramic Multilayer Electronic Component	29	848	12/17/92